

Combine Type Connector (for SD Memory Card, MultiMediaCard™, Memory Stick™)

SCDB Series



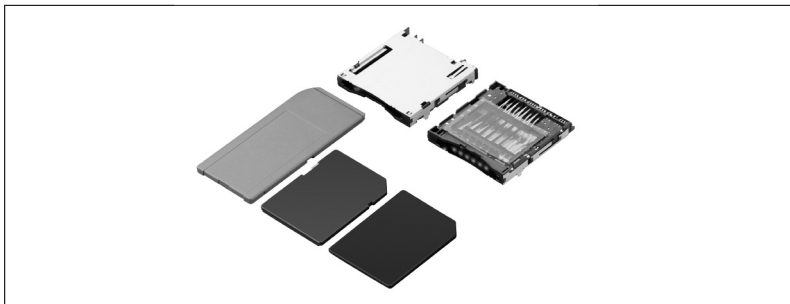
Push-push type featuring contact protection function with less impact to media cards.

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
Memory
Stick Micro™



Combine Type

For
W-SIM

Typical Specifications

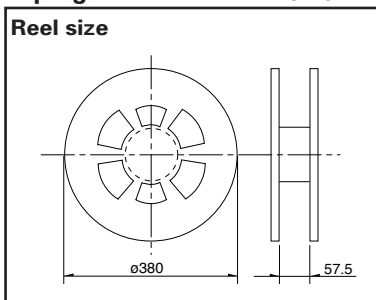
Items			Specifications
Structure	Applicable media		SD Memory Card, MultiMediaCard™, Memory Stick™
	Mounting type		Surface mounting type
	Mounting style		Standard mount/ Reverse mount
	Media ejection structure		Push-push type
Performance	Operating temperature range		−20°C to +60°C
	Voltage proof		100V AC 1minute
	Insulation resistance (Initial)		1,000MΩ min.
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
	Insertion and removal cycle		10,000cycles (SD Memory Card) 12,000cycles (Memory Stick™)

Product Line

Media ejection structure	Mounting system	Feature	Stand-off(mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	With boss	0	Taping	SCDB3A0202	1
	Reverse mount				SCDB4A0101	2

Packing Specifications

Taping Unit:mm



Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
1 reel	1 case /Japan	1 case /export packing		
300	600	1,200	56	403 × 403 × 297

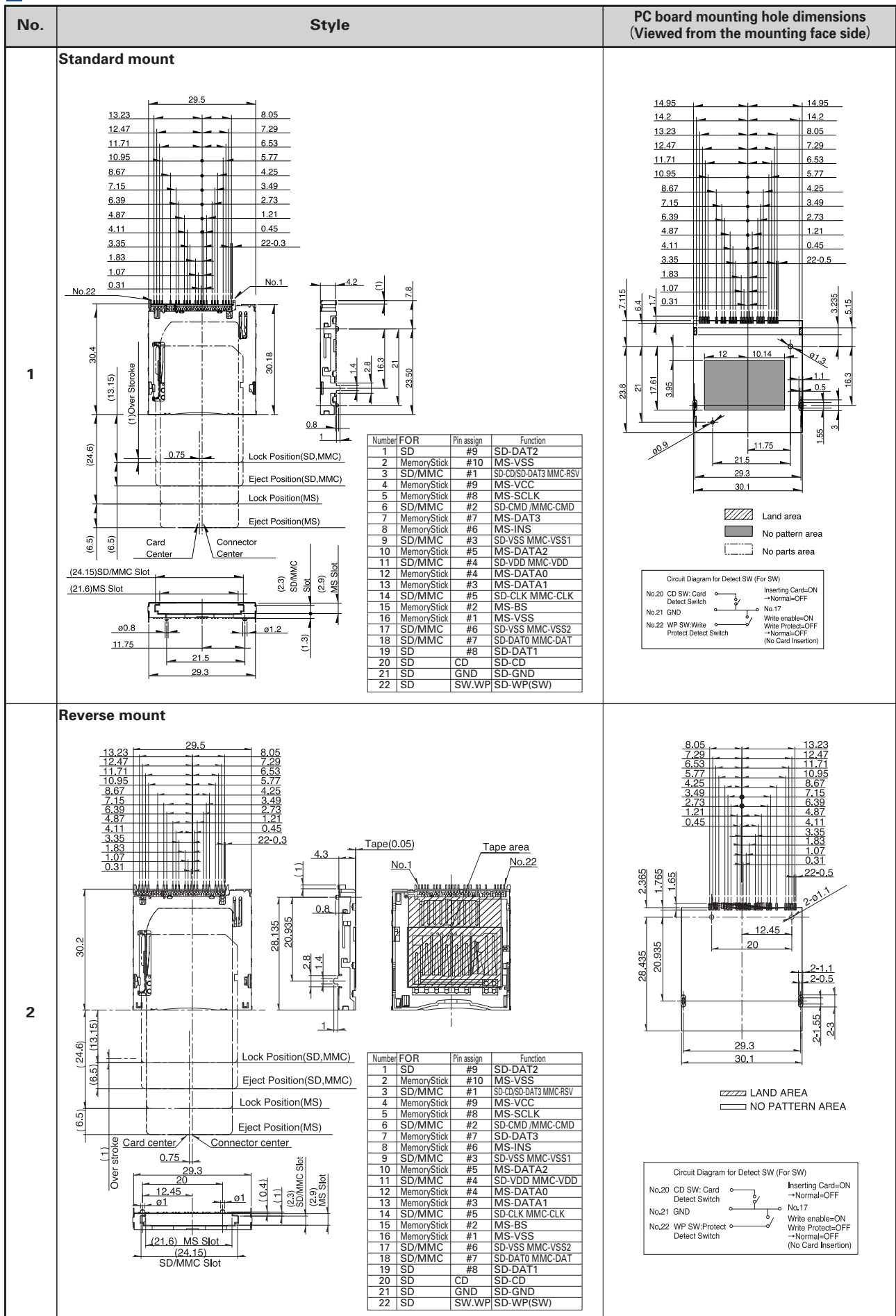
Note

Please place purchase orders per minimum order unit N (integer).

Refer to P.558 for soldering conditions.

Unit:mm

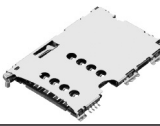
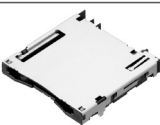
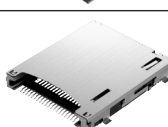
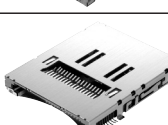
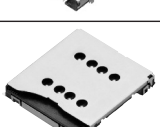
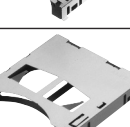
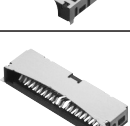
Dimensions

For
SD Memory
CardFor
microSD™
CardFor
SIM Card
8pinsFor
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Combine Type

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W-SIM

List of Varieties

Applicable media		Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page			
SIM Card 8pins		SCGC1B0101		Push-push type	Standard mount	With switch	0		541			
		SCGC1B0301				With Automatic Locking Cam						
Memory Stick Micro™		SCNA1A0300				Without boss		With boss	543			
Combine Type		SCDB3A0202			Reverse mount	545						
		SCDB4A0101										
		SD Memory Card Multi-Media Card™ Multi-Media Card Plus™ Memory Stick™ xD-Picture Card™			SCDG1A0101						Standard mount	547
					SCDG2A0101						Reverse mount	
SD Memory Card Multi-Media Card™ Memory Stick™ xD-Picture Card™		SCDG4B0100		Push-push type Manual insertion/removal	Standard mount	Thin with a Thickness of 4.2mm		—	549			
microSD™ Card		SCHG1B0100				microSD™ Card right insertion type			551			
SIM Card 8pins												
W-SIM		SCZA1A0100		Push-push type	Standard mount	Without boss L type		553				
		SCZA1A0200				With boss L type						
		SCZA1A0300				Without boss 0.6mm type						
		SCZA1A0400				With boss 0.6mm type						
		SCZA1A0500				Without boss 1.2mm type						
		SCZA1A0600				With boss 1.2mm type						
		SCZA2A0100			Manual insertion/removal	With boss L type						
		SCZA2A0200							Without boss 0.6mm type			

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM

Note

○marks in "Available for automotive use" indicate that some of the series products can work at the operating temperature range from -40°C to +85°C.

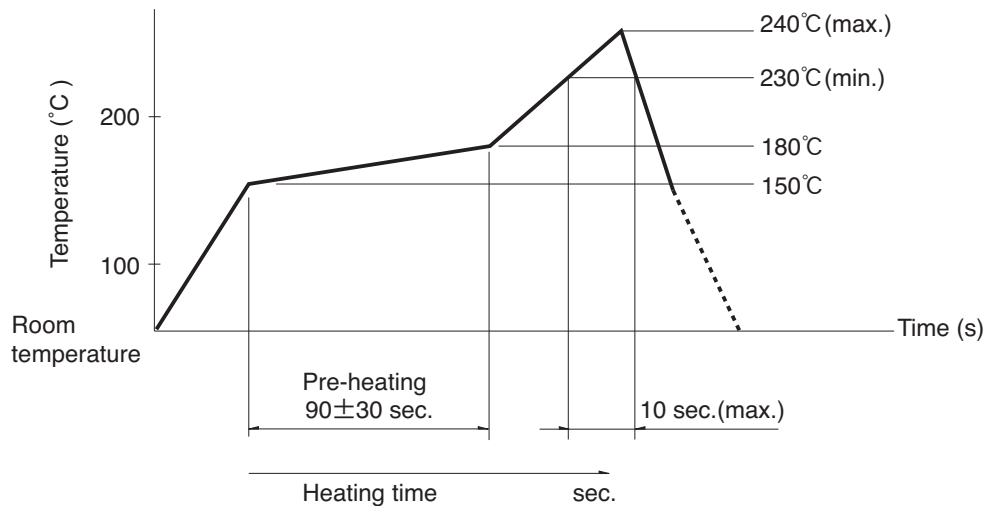
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

1.Connector handling precautions

- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.

If you wash it, it may cause deterioration of mechanically and electrically.

If washing is necessary, please make contact with us beforehand.

2.When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions.

Caution is therefore required.

3.When soldering, do not use water soluble flux because this may corrode the product.

4.regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.

5.As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.

6.Please do not solder at the ejector pushing position.

7.To prevent contact disturbance by the sulfuration or oxidation of the contact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.

- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorine gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding direct sunlight. The connectors shall be used as soon as possible.

8.Don't push or hold down the metal cover of the connector, otherwise there is a possibility that the card would not be ejected or influences to other function.

9.Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.

- Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- Establish CR accumulation circuit.

10.This product does not operate normally when the card which does not conform to the specification is used occasionally.

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